

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5880045

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KAIAM CORP.	05/21/2019
RECEIVING PARTY DATA	
Name:	KAIAM LLC
Street Address:	39677 EUREKA DR.
City:	NEWARK
State/Country:	CALIFORNIA
Postal Code:	94560
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16366995
CORRESPONDENCE DATA	
Fax Number:	(650)712-0263
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6507120340
Email:	motts@hmbay.com
Correspondent Name:	HAYNES BEFFEL & WOLFELD LLP
Address Line 1:	637 MAIN STREET
Address Line 2:	PO
Address Line 4:	HALF MOON BAY, CALIFORNIA 94019
ATTORNEY DOCKET NUMBER:	BRDX 3025-3
NAME OF SUBMITTER:	MATHEW OTTS
SIGNATURE:	/Mathew Otts/
DATE SIGNED:	12/20/2019
Total Attachments: 2	
source=00727345#page1.tif	
source=00727345#page2.tif	

CONFIRMATION OF ASSIGNMENT OF PATENT RIGHTS

WHEREAS, the undersigned Kaiam Corporation (hereinafter "Assignor") a California Corporation having a business address at 39677 Eureka Drive, CA 94560, US, has assigned various patent properties and attendant rights to Kaiam (assignment for the benefit of creditors) LLC (hereinafter "Assignee"), a California limited liability company, by way of an instrument entitled general assignment, dated January 17th, 2019.

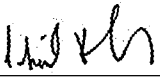
NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by Assignor to have been received in full from said Assignee, Assignor and Assignee confirm the following:

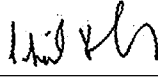
1. Assignor has sold, assigned, transferred and conveyed unto said Assignee the entire right, title and interest (a) in and to the Assigned Patents and Patent Applications as set forth in the attached Schedule A and to the inventions described in these patents and applications; (b) in and to all rights to apply for foreign patents on based upon said patents and patent applications pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said inventions in the United States or any foreign country (including rights to all past and future damages arising from infringement of these patents), including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents (collectively the "patent properties").

IN WITNESS WHEREOF, Assignee and Assignor have executed this instrument as of the dates written below.

Date: 05/21/2019

Date: 05/21/2019

Signed: 

Signed: 

Name: Michael A. Maidy

Name: Michael A. Maidy

Title: Signed on behalf of Assignor under power of attorney granted by General Assignment Agreement dated 1/17/19
Assignor

Title: Manager
Assignee

Schedule A

Patent number	Application number	Filing Date (m/d/y)	Country/Region	Title
	15/373991	12/09/2016	US	Optical Transceiver With Combined Transmitter and Receiver Assembly
9722706			US	Multiple Wavelength Light-source With Tracking Multiplexer
9768901			US	Planar Lightwave Circuit Active Connector
10054739			US	Qsfp Double Density Module
10178452			US	Optical Interconnect Having Optical Splitters And Modulators Integrated On Same Chip
	15/706457	9/15/2017	US	Optical Module For Terabit Switch
	16/366995	3/27/2019	US	Optical Module For Terabit Switch (continuation application)
8902944			US	High Power Multi-Wavelength Laser Source
	15/369649	12/05/2016	US	Optical Transceiver
	62/678907	05/31/2018	US	PLC Silica to Silicon Nitride Mode Transformer for Hybrid Devices
	62/673687	18/05/2018	US	PLC Wafer Level Test and Subassembly
	15860742.4A	9/15/2017	EP	Planar Lightwave Circuit Active Connector
	17770998.7A	10/19/2018	EP	Optical Interconnect Having Optical Splitters And Modulators Integrated On Same Chip
	201680079324.6A	7/18/2018	China	Optical Transceiver With Combined Transmitter and Receiver Assembly
	201780027559.5A	11/02/2018	China	Optical Interconnect Having Optical Splitters And Modulators Integrated On Same Chip